**Product data sheet** 

# 1. General description

Ultrafast power diode in TO-263 (D2PAK) plastic package.

### 2. Features and benefits

- · Low forward voltage drop
- Low leakage current
- Soft reverse recovery characteristics
- · High thermal cycling performance

## 3. Applications

- Home appliance power supply
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit	
Absolute	maximum rating						
$V_{RRM}$	repetitive peak reverse voltage		600			V	
$I_{F(AV)}$	average forward current	$\delta$ = 0.5 ; square-wave pulse; $T_{mb} \le 150$ °C; Fig. 1; Fig. 2; Fig. 3	9		А		
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5 ; $t_p$ = 25 $\mu$ s; $T_{mb} \le$ 150 °C; square-wave pulse		18		Α	
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	120			Α	
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse;	132			Α	
Symbol	Parameter	Conditions	Min Typ Max		Unit		
Static ch	aracteristics						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 8 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>		-	1.05	1.3	V
		I <sub>F</sub> = 8 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>		-	0.9	1.1	V
Dynamic	characteristics						
t <sub>rr</sub>	reverse recovery time	$I_F = 1 \text{ A}$ ; $V_R = 30 \text{ V}$ ; $dI_F/dt = 100 \text{ A/}\mu\text{s}$ ; $T_j = 25 \text{ °C}$ ; Fig. 7		-	40	75	ns

# 5. Pinning information

**Table 2. Pinning information** 

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected		K — A
2	K	cathode		001aaa020
3	Α	anode		
mb	К	mounting base; connected to cathod	N P	

<sup>[1]</sup> it is not possible to make connection to Pin 2 of the TO263 package.

# 6. Ordering information

**Table 3. Ordering information** 

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYV29B-600P	TO263	BYV29B-600PJ	Reel	800	TO263N (N)	26-Sep-2016
					TO263P (P)	12-Jun-2023

# 7. Marking

**Table 4. Marking codes** 

Type number	Marking codes		
	Assembly factory: N	Assembly factory: P	
BYV29B-600P	BYV29B	BYV29B	
	600P	600P	
	PJNxxxx xx	PJPxxxx xx	

# 8. Limiting values

#### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		600	V
$V_{\text{RWM}}$	crest working reverse voltage		600	V
$V_R$	reverse voltage	DC	600	V
I <sub>F(AV)</sub>	average forward current	$δ$ = 0.5; square-wave pulse; $T_{mb} \le 150$ °C; Fig. 1; Fig. 2; Fig. 3	9	А
I <sub>FRM</sub>	repetitive peak forward current	$δ = 0.5$ ; $t_p = 25 \mu s$ ; $T_{mb} \le 150 °C$ ; square-wave pulse	18	А
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	120	А
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse;	132	Α
T <sub>stg</sub>	storage temperature		-55 to 175	°C
T <sub>j</sub>	junction temperature		175	°C

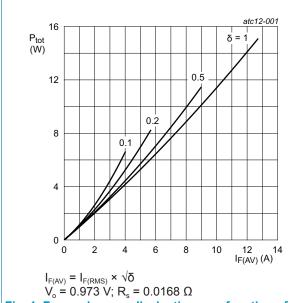
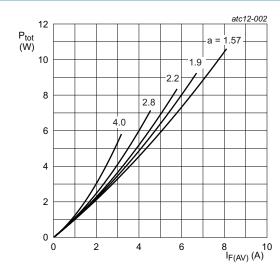
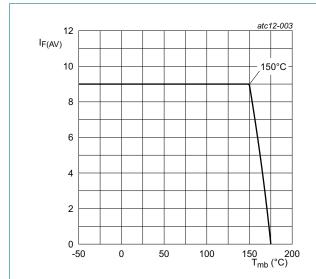


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor =  $I_{F(RMS)}/I_{F(AV)}$ Vo = 0.973 V; Rs = 0.0168  $\Omega$ 

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values





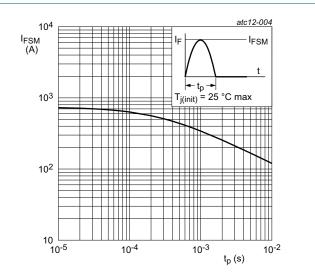
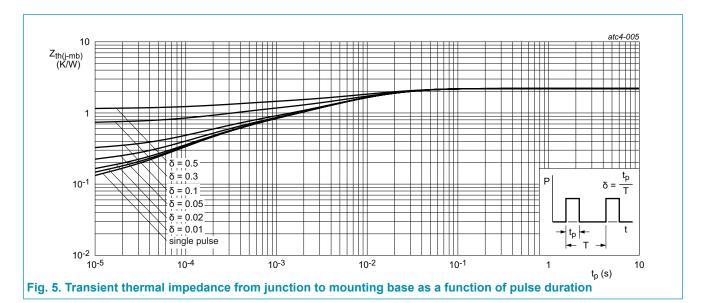


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

## 9. Thermal characteristics

#### **Table 6. Thermal characteristics**

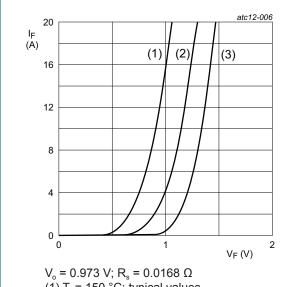
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	<u>Fig. 5</u>	-	-	2.2	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	50	-	K/W



### 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	aracteristics			'		
$V_{F}$	forward current	I <sub>F</sub> = 8 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	1.05	1.3	V
		I <sub>F</sub> = 8 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>	-	0.9	1.1	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C	-	-	10	μA
		V <sub>R</sub> = 600 V; T <sub>j</sub> = 150 °C	-	-	0.4	mA
Dynamic	characteristics			'		
Q <sub>r</sub>	reverse charge	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	55	-	nC
t <sub>rr</sub>	reverse recovery time	$I_F = 1 \text{ A}$ ; $V_R = 30 \text{ V}$ ; $dI_F/dt = 100 \text{ A/}\mu\text{s}$ ; $T_j = 25 \text{ °C}$ ; Fig. 7	-	40	75	ns
I <sub>RM</sub>	peak reverse recovery current	$I_F = 1 \text{ A}$ ; $V_R = 30 \text{ V}$ ; $dI_F/dt = 50 \text{ A/}\mu\text{s}$ ; $T_j = 25 \text{ °C}$ ; Fig. 7	-	1.9	-	А
		$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	2.8	-	А



(1)  $T_j = 150$  °C; typical values (2)  $T_j = 150$  °C; maximum values (3)  $T_i = 25$  °C; maximum values

Fig. 6. Forward current as a function of forward voltage

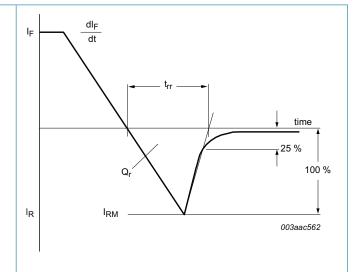
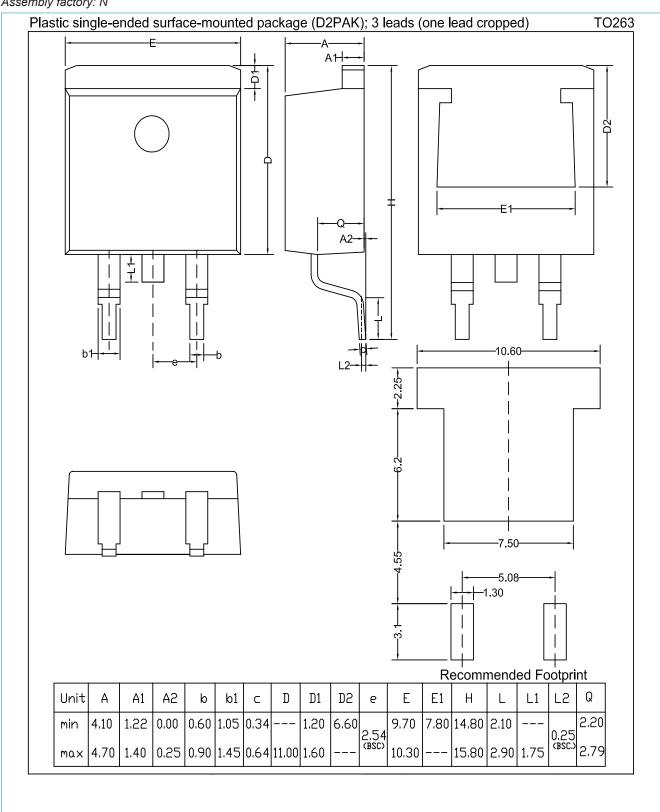


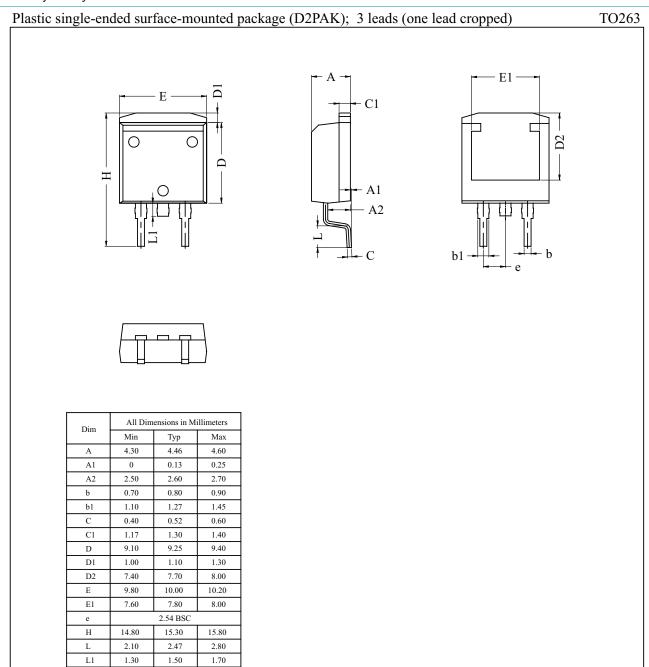
Fig. 7. Reverse recovery definitions; ramp recovery

# 10. Package outline

Assembly factory: N



### Assembly factory: P



### 11. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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**BYV29B-600P** 

**Ultrafast power diode** 

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